

ISO9001 & ISO14001 & TS16949 CHILISIN ELECTRONICS CORP.

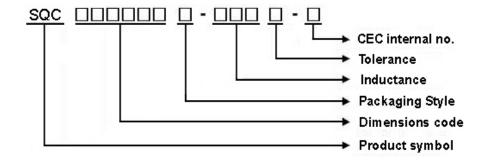
Lead-Free & RoHs Compliance!!

SPECIFICATION FOR APPROVAL

CUSTOMER:			
CUSTOMER P/N:			
OUR DWG No:			
QUANTITY:	0 Pc	s. DATE:	2013/04/10
ITEM:		SQC322520T-	SERIES
	SPECI	FICATION	
		PTED BY:	
COMPONENT ENGINEER			
ELECTRICAL ENGINEER			
MECHANICAL ENGINEER			
APPROVED			
REJECTED			
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DRAWN BY		CKED BY	APPROVED BY
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- 1 Scope: This specification applies to CHIP COIL
- 2 Part Numbering: Product Identification



3 Rating:

Operating Temperature: $-40 \, ^{\circ}\text{C} \sim 125 \, ^{\circ}\text{C}$ (Including self - temperature rise)

Storage Temperature: Under $2.5\,^{\circ}\mathrm{C}$,Humidity < 75% RH

4 Marking:



Ex: SQC322520T-4R7M-N

Marking: 4R7

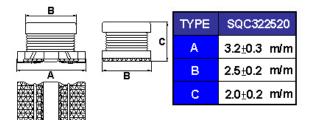
Marking color: Black

5 Standard Testing Condition

	Unless otherwise specified	In case of doubt
Temperature	Ordinary Temperature(15 to 35°ℂ)	20±2 ℃
Humidity	Ordinary Humidity(25 to 85% RH)	60 to 70 % RH



6 Configuration and Dimensions:



7 ELECTRICAL CHARACTERISTICS :

Part No.	Inductance (uH)	Test Freq.	SRF (MHz)Min.	RDC (Ω)	Rated Current (A)	Tolerance	Marking
SQC322520T-R15□-N	0.15	0.1V 1MHz	400	0.028±30%	1.45	М	R15
SQC322520T-R47□-N	0.47	0.1V 1MHz	150	0.042±30%	1.1	М	R47
SQC322520T-1R0□-N	1	0.1V 1MHz	96	0.09±30%	1	М	1R0
SQC322520T-2R2□-N	2.2	0.1V 1MHz	64	0.13±30%	0.6	М	2R2
SQC322520T-3R3□-N	3.3	0.1V 1MHz	60	0.15±30%	0.6	K,M	3R3
SQC322520T-3R9□-N	3.9	0.1V 1MHz	50	0.16±30%	0.5	М	3R9
SQC322520T-4R7□-N	4.7	0.1V 1MHz	43	0.20±30%	0.45	М	4R7
SQC322520T-6R8□-N	6.8	0.1V 1MHz	30	0.26±30%	0.4	М	6R8
SQC322520T-100□-N	10	0.1V 1MHz	26	0.44±30%	0.3	K,M	100
SQC322520T-150□-N	15	0.1V 1MHz	22	0.55±30%	0.35	K,M	150
SQC322520T-220□-N	22	0.1V 1MHz	19	0.71±30%	0.25	K,M	220
SQC322520T-270□-N	27	0.1V 1MHz	15	0.90±30%	0.23	K,M	270
SQC322520T-330□-N	33	0.1V 1MHz	15	1.1±30%	0.2	K,M	330
SQC322520T-470□-N	47	0.1V 1MHz	15	1.30±30%	0.17	K,M	470
SQC322520T-560□-N	56	0.1V 1MHz	12	2.30±30%	0.15	K,M	560
SQC322520T-101□-N	100	0.1V 1MHz	10	3.50±30%	0.1	K,M	101
SQC322520T-151□-N	150	0.1V 1MHz	7	6.0±30%	0.08	J,K,M	151
SQC322520T-221□-N	220	0.1V 1MHz	6.8	8.40±30%	0.07	J,K,M	221
SQC322520T-271□-N	270	0.1V 1MHz	6	10±30%	0.065	K,M	271
SQC322520T-331□-N	330	0.1V 1MHz	5.6	10±30%	0.06	J,K,M	331
SQC322520T-391□-N	390	0.1V 1MHz	5	17±30%	0.06	K,M	391
SQC322520T-471□-N	470	0.1V 1kHz	5	19±30%	0.06	K,M	471
SQC322520T-561□-N	560	0.1V 1kHz	5	22±30%	0.06	K,M	561

NOTE: □-tolerance J=±5% / K=±10% / M=±20%

^{1.}Operating temperature range $-4~0~\text{C}\sim1~2~5~\text{C}$ (Including self - temperature rise)

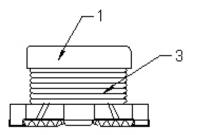
^{2.}Rated Current: Self temperature rise shall be limited to 35℃ Max.Inductance drop 10% typ.

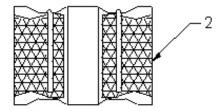
[&]quot;-N" FOR COMPLETELY LEAD FREE TYPE(INCLUDING FERRITE BODY & SOLDER)



8 SQC322520T Series

8.1 Construction:





8.2 Material List:

ITEM	PART	DESCRIPTION	SUPPLIES
1	CORE	FERRITE	CHILISIN
2	TERMINAL	Sn/Ag3.0/Cu0.5	Dyfenco
3	WIRE	Copper wire	



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SQC322520T Series Specification

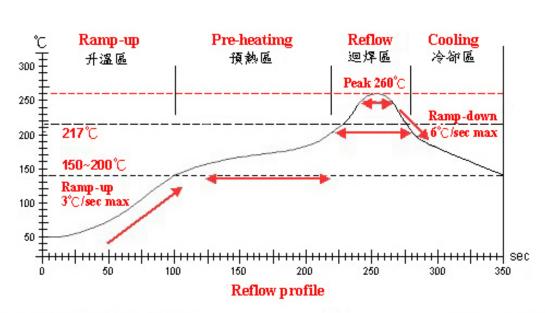
9 Reliability Of Ferrite Wire Wound Chip Coil 1-1.Mechanical Performance

	Item	Specification	Test Method
1-1-1	Shear Test	Chip coil shall not be	Substrate: 4.5 Chip Ciol
		damaged after tested as test method	Glass-epoxy substrate Patter Solder resist Substrate
			Solder:Sn/Ag3.0/Cu0.5
			Applied Direction:
			Force: 10N Substrate Hold Duration:5s±1s
1 1 2	Bending Test	1	Substrate:Glass-epoxy substrate(100mm*40mm*1.6mm)
1-1-2	bending rest		speed of Applying Force:1mm/s
			Deflection:2mm
			Hold Duration:30s Deflection 45 Product (in nn)
1-1-3	Vibration		Oscillation Frequency:10Hz to 55 Hz to 10 hZ for 1 min Total Amplitude:1.5mm Testing Time:A period of 2 hours in each of 3 mutually
1_1_4	Solderability	The wetting area of the	perpendicular directions(Total 6 hours) Solder:Sn/Ag3.0/Cu0.5
	,	electrode shall be at least 95% covered with new solder coating	per-Heating:150°ℂ±10°ℂ/1min to 2min solder Temperature:245°ℂ±5°ℂ Immersion Time:4s±1s
	Resistance to Soldering Heat	Appearance:No damage	Solder:Sn/Ag3.0/Cu0.5 per-Heating:150°C±10°C/1min to 2min solder Temperature:260°C±5°C Immersion Time:10s±1s
1-1-6	Resistance to solvent	There must be no change in appearance or obliteration of marking.	Inductors must withstand 6 minutes of alcohol or water.

1.2 Environmental Performance

1-Z.E	nvironmental Perfo	rmance	_		
No	ltem	Specification	Test Method		
1-2-1	Heat Resistance	Appearance: No damage	Temperature:85°C±3°C		
		Inductance Change:within±10%	Time:1000h		
		_	Then measured after exposure in the room		
			Condition for 24h±2h		
1-2-2	Cold Resistance	1	Temperature: -40°C±3°C		
			Time:1000h		
			Then measured after exposure in the room		
			Condition for 24h±2h		
1-2-3	Humidity		Temperature: 40°C±2°C		
			Humidity:90%(RH) to 95%(RH)		
			Time:1000h		
			Then measures after exposure in the room		
			Condition for 24h±2h		
1-2-4	Temperature Cycle		One cycle:		
			Step Temperature (°C) Time (min)		
			1 -40±3 30		
			2 25±2 3		
			3 125±3 30		
			4 25±2 3		
			Total: 100cycles		
			Measured after exposure in the room condition for 24hrs		





Lead-Free(LF) 標準溫度分析範圍

Refer to J-STD-020C

管制項目 Item.	升溫區 Ramp-up	預熱區 Pre-heatimg	迴焊區 Reflow	Peak Temp	冷卻區 Cooling
溫度範圍 Temp.scope	R.T. ~150°C	150°C ~ 200°C	217℃	260±5 ℃	Peak Temp. ~ 150°C
標準時間 Time spec.	_	60 ~ 180 sec	60 ~ 150 sec	20 ~ 40 sec	_
實際時間 Time result	<u> </u>	75 ~ 100 sec	90 ~ 120 sec	5 ~ 10 sec	_



11 PACKAGING

11.1 Packaging -Cover tape

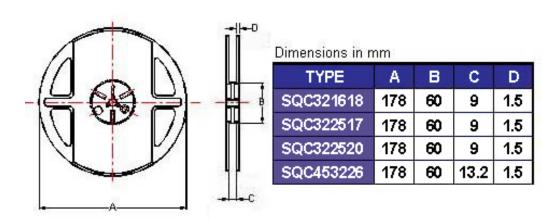
The force for tearing off cover tape is 10 to 100 grams in the arrow direction.



11.2 Packaging Quantity

TYPE	BULK	PCS/REEL
SQC321618	✓	2000
SQC322517	✓	2000
SQC322520	✓	2000
SQC453226	✓	500

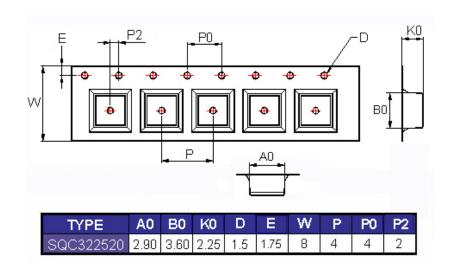
11.3 Reel Dimensions



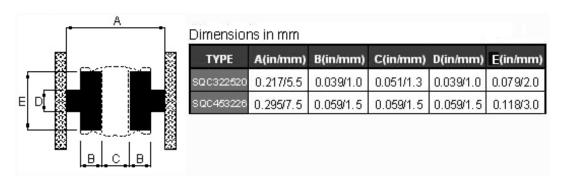


11 PACKAGING

11.4 Tape Dimensions in mm



12 Recommended Pattern



13 Note:

- 1. Please make sure that your product is has been evaluated and confirmed against your specifications when our product is mounted to your product.
- 2. Do not knock nor drop.
- 3. All the items and parameters in this product specification have been prescribed on the premise that our product is used for the purpose, under the condition and in the environment agreed upon between you and us. You are requested not to use our product deviating from such agreement.
- 4. Please keep the distance between transformer/coil and other components (refer to the standard IEC 950)



13 Note:

5. Storage and Handing Requirements

(1)Storage period

Use the products within 12 months after delivered Solderability should be checked if this period is exceeded

(2)Storage conditions

*Products should be stored in the warehouse on the following conditions

Temperature: -10°C ~ 40°C

Humidity : $30\% \sim 70\%$ relative humidity no rapid change on temperature and humidity The electrode of the products is coated with solder.Don't keep products in corrosive gases such as sulfur, chlorine gas or acid, or it may cause oxidization of electrode, resulting in poor solderability.

- *Products should not be storaged on bulk packaging condition to prevent the chipping of the core and the breaking of winding wire caused by the collision between the products.
- *Products should be storaged on the palette for the prevention of the influence from humidity, dust and so on.
- *Products should be storaged in the warehouse without heat shock, vibration, direct sunlight and so on.

(3)Handing Condition

Care should be taken when transporting or handing product to avoid excessive vibration or mechanical shock.